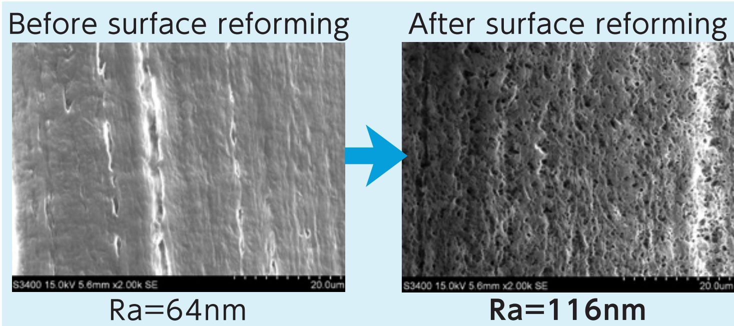
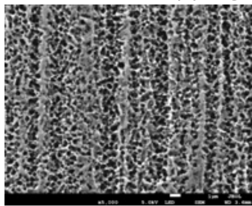
TOP LECS PROCESS

Electroless copper plating process for LCP
Toward next-generation high speed communication

High adhesion to low Ra material

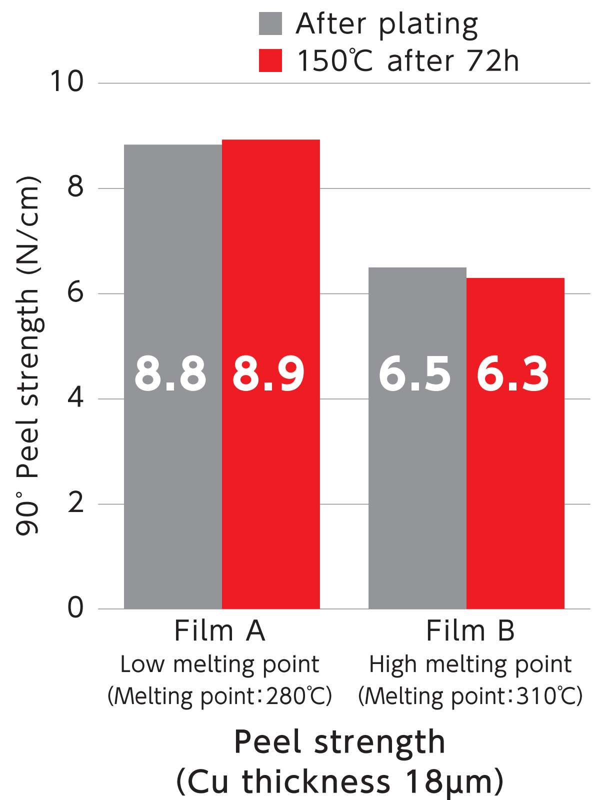


Conventional LCP-CCL substrate
(LCP surface after stripping Cu foil)



Ra=284nm

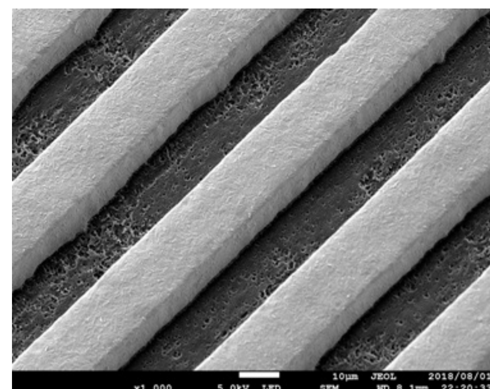
Not increase surface roughness, can realize high adhesion



Peel strength
(Cu thickness 18µm)

Electroless Cu plating by R to R plating equipment

Excellent in fine patterning performance



L/S=20/20µm

Decrease Pd adsorption for fine patterning performance